



ALPHA & OMEGA
SEMICONDUCTOR

AO4618

40V Complementary MOSFET

General Description

The AO4618 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This complementary N and P channel MOSFET configuration is ideal for low Input Voltage inverter applications.

Product Summary

N-Channel

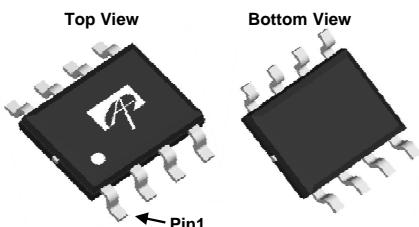
$V_{DS} = 40V$
 $I_D = 8A$ ($V_{GS}=10V$)
 $R_{DS(ON)}$
 $< 19m\Omega$ ($V_{GS}=10V$)
 $< 27m\Omega$ ($V_{GS}=4.5V$)
100% UIS Tested
100% R_g Tested

P-Channel

$-40V$
 $-7A$ ($V_{GS}=-10V$)
 $R_{DS(ON)}$
 $< 23m\Omega$ ($V_{GS}=-10V$)
 $< 30m\Omega$ ($V_{GS}=-4.5V$)
100% UIS Tested
100% R_g Tested

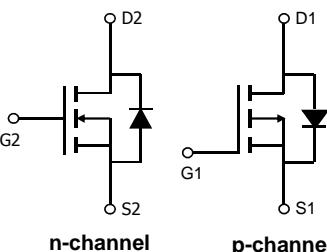
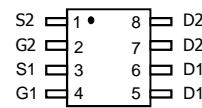


SOIC-8



Bottom View

Top View



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage	V_{DS}	40	-40	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current	I_D	8	-7	A
Current $T_A=70^\circ C$		6	-5.5	
Pulsed Drain Current ^C	I_{DM}	40	-35	
Avalanche Current ^C	I_{AS}	15	-35	A
Avalanche energy $L=0.1mH$ ^C	E_{AS}	11	61	mJ
Power Dissipation ^B	P_D	2	2	W
$T_A=25^\circ C$		1.3	1.3	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10s$	$R_{\theta JA}$	48	62.5	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		74	90	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	32	40	°C/W

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			±100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.4	1.9	2.4	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=8\text{A}$ $T_J=125^\circ\text{C}$		15.4	19	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=4\text{A}$		22.5	29	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=8\text{A}$		21	27	S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	0.75	1		V
I_S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=20\text{V}, f=1\text{MHz}$		415		pF
C_{oss}	Output Capacitance			112		pF
C_{rss}	Reverse Transfer Capacitance			11		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	1	2.2	3.5	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, I_D=8\text{A}$		6.5	12	nC
$Q_g(4.5\text{V})$	Total Gate Charge			3	6	nC
Q_{gs}	Gate Source Charge			1.2		nC
Q_{gd}	Gate Drain Charge			1.1		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, R_L=2.5\Omega, R_{\text{GEN}}=3\Omega$		4		ns
t_r	Turn-On Rise Time			3		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			15		ns
t_f	Turn-Off Fall Time			2		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=8\text{A}, dI/dt=100\text{A}/\mu\text{s}$		12.5		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=8\text{A}, dI/dt=100\text{A}/\mu\text{s}$		3.5		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{ C}$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{ C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.

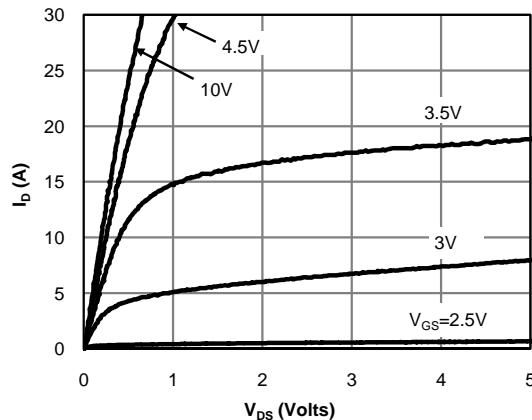
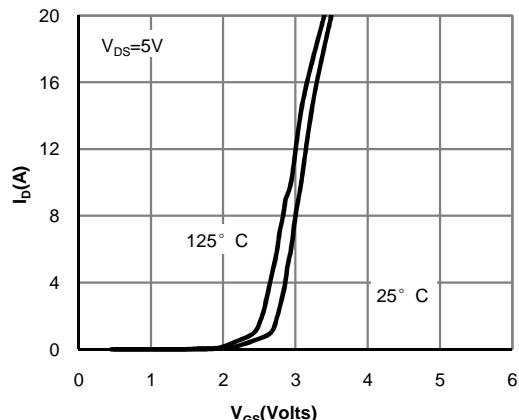
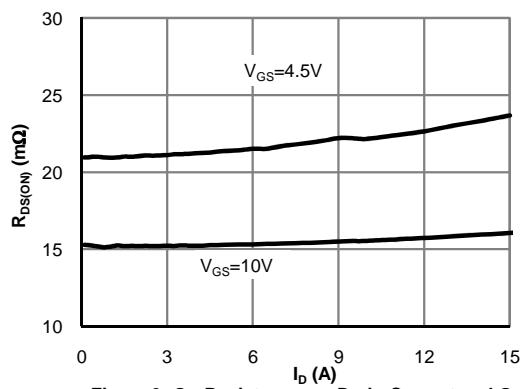
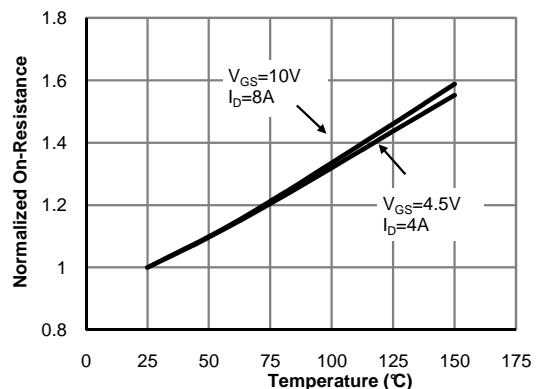
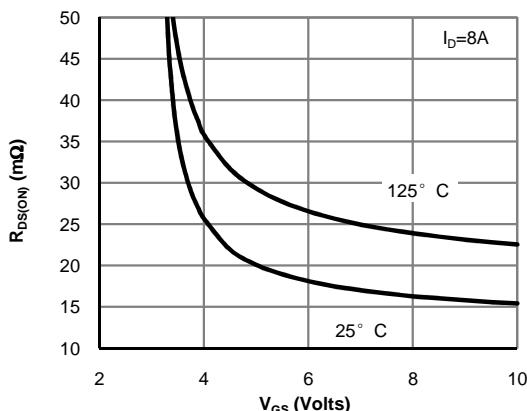
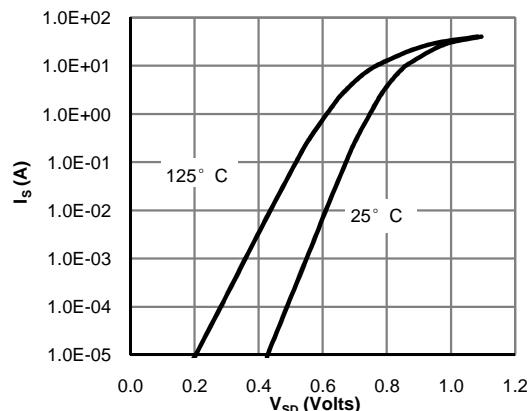
C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{ C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{ C}$.

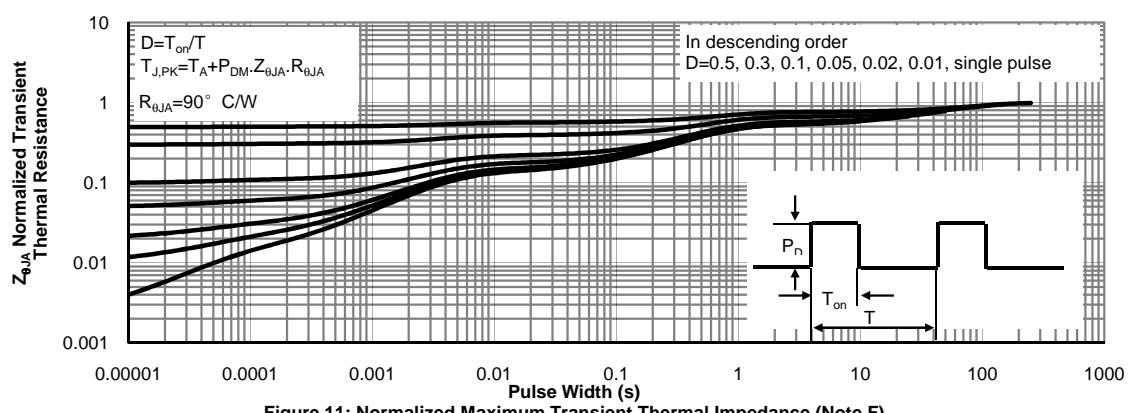
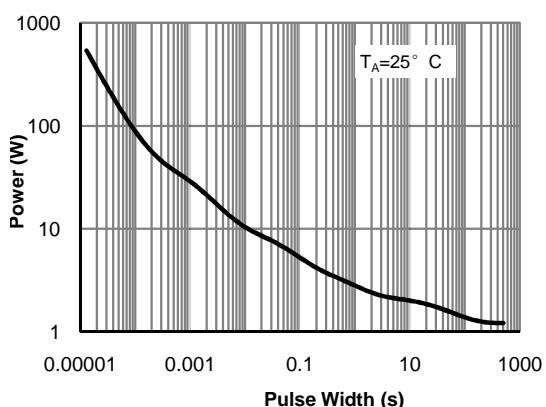
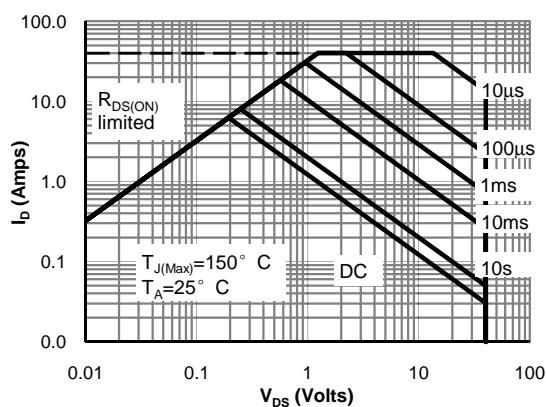
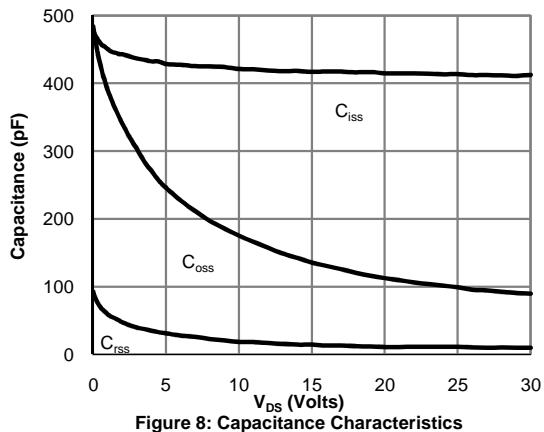
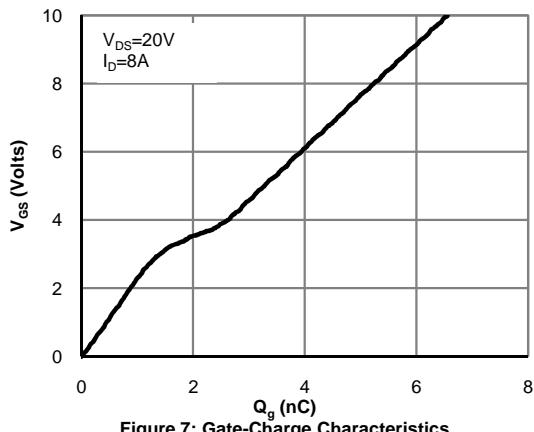
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

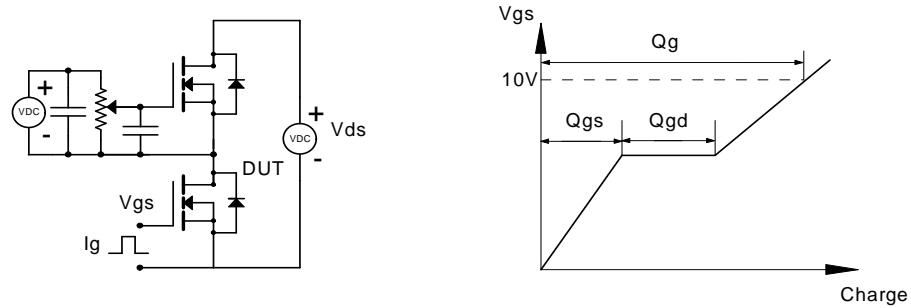
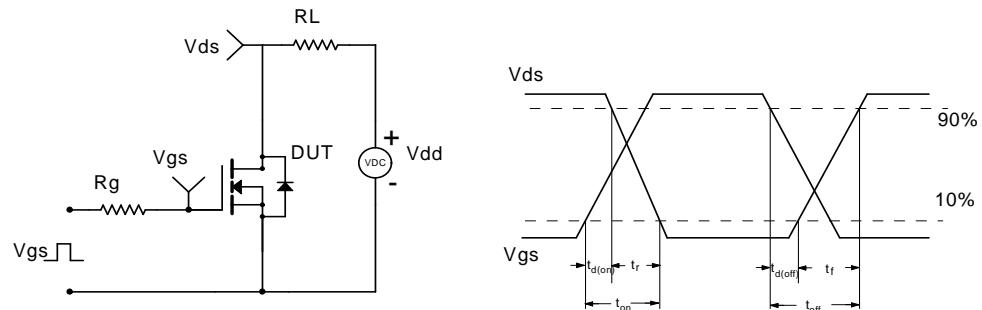
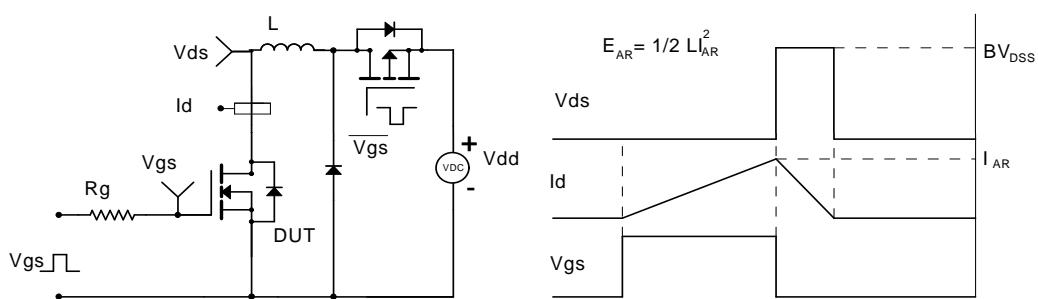
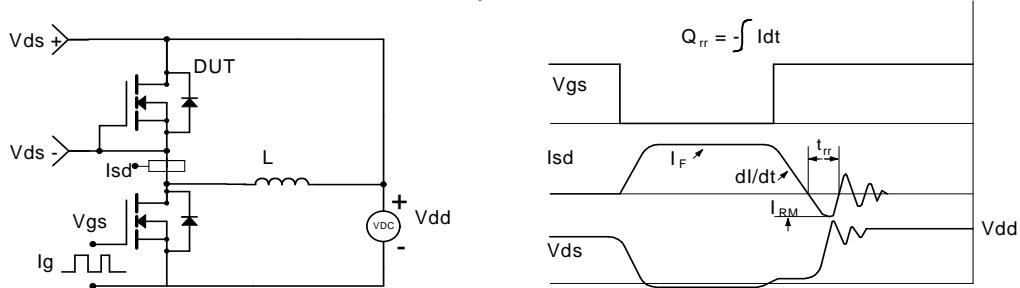
E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{ C}$. The SOA curve provides a single pulse rating.

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N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms




P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-40\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			±100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.7	-1.9	-3	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-7\text{A}$ $T_J=125^\circ\text{C}$		19 28.5	23 35	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-4\text{A}$		24	30	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-7\text{A}$		26		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.74	-1	V
I_S	Maximum Body-Diode Continuous Current				-2.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-20\text{V}, f=1\text{MHz}$		1870		pF
C_{oss}	Output Capacitance			185		pF
C_{rss}	Reverse Transfer Capacitance			155		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		4.5	9	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=-20\text{V}, I_D=-7\text{A}$		32	45	nC
$Q_g(4.5\text{V})$	Total Gate Charge			8	12	nC
Q_{gs}	Gate Source Charge			7.6		nC
Q_{gd}	Gate Drain Charge			6.2		nC
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=-20\text{V}, R_L=2.8\Omega, R_{\text{GEN}}=3\Omega$		10		ns
t_r	Turn-On Rise Time			18		ns
$t_{D(\text{off})}$	Turn-Off DelayTime			38		ns
t_f	Turn-Off Fall Time			24		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-7\text{A}, dI/dt=500\text{A}/\mu\text{s}$		13		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-7\text{A}, dI/dt=500\text{A}/\mu\text{s}$		33		nC

A. The value of R_{QJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

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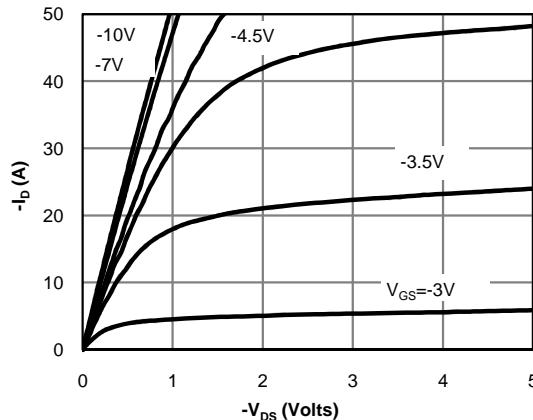
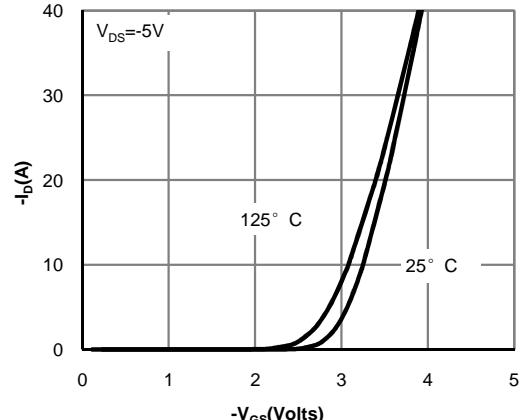
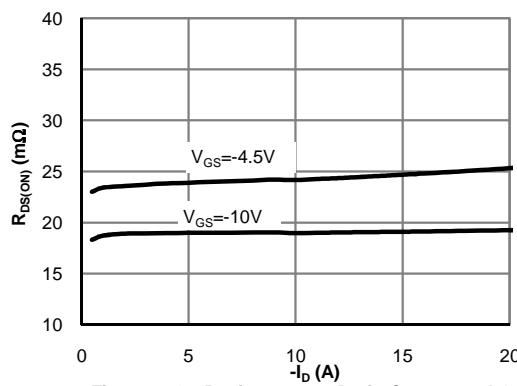
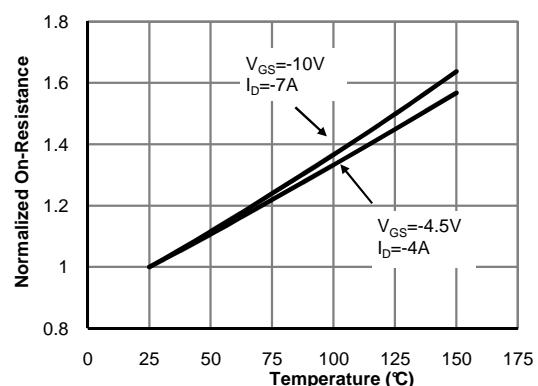
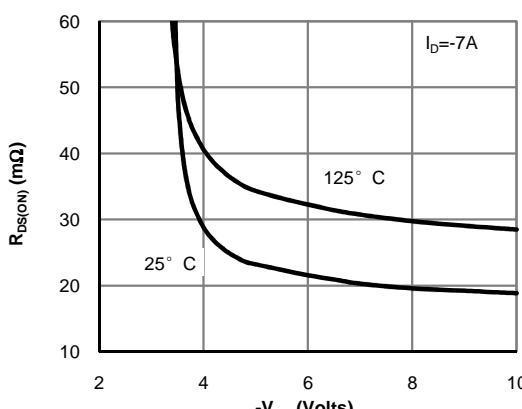
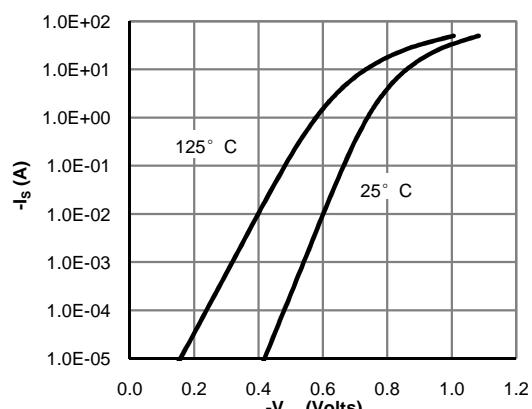
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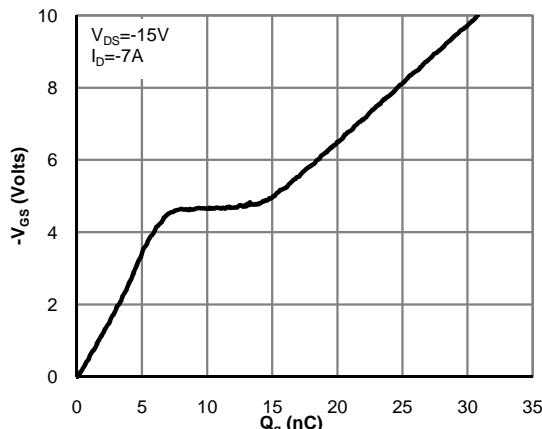
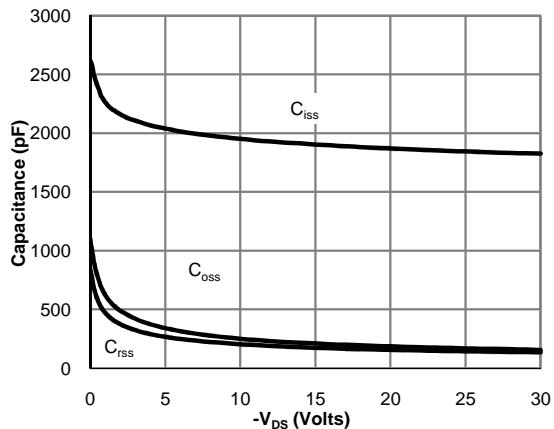
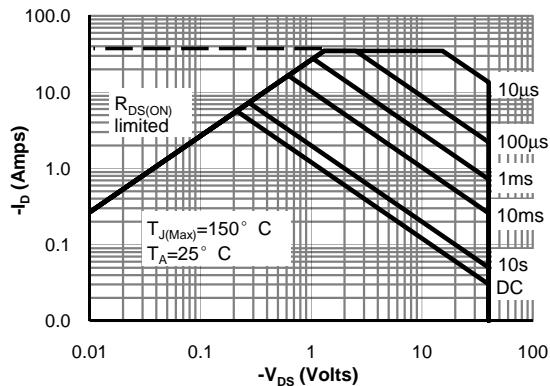
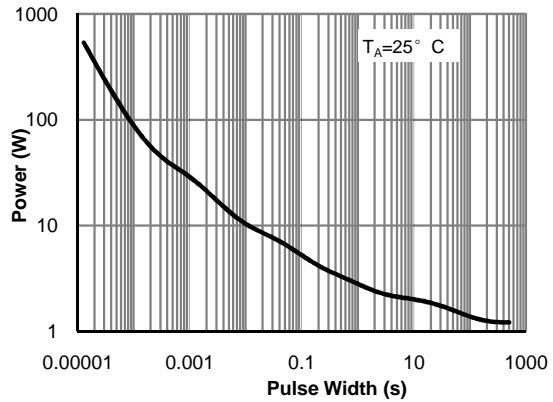
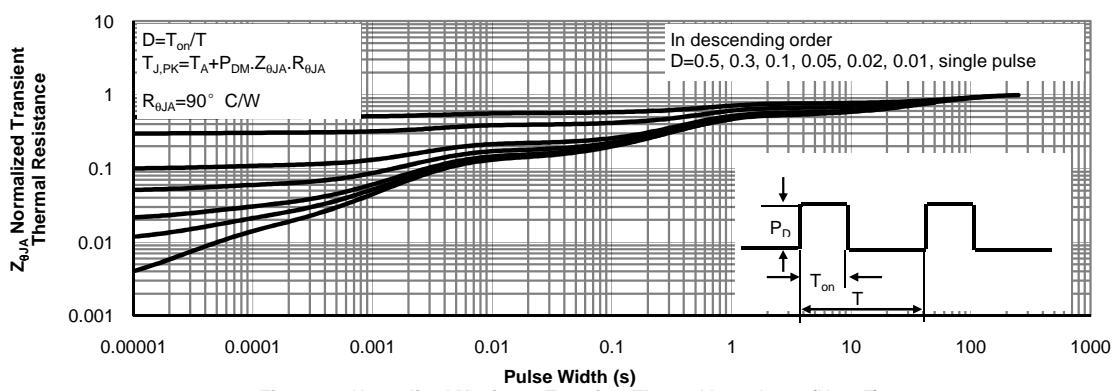
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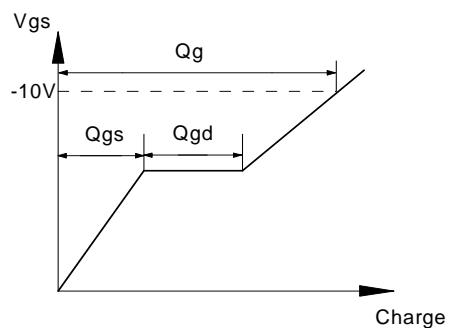
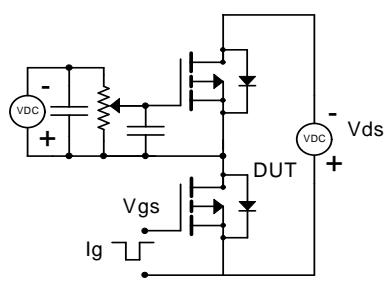
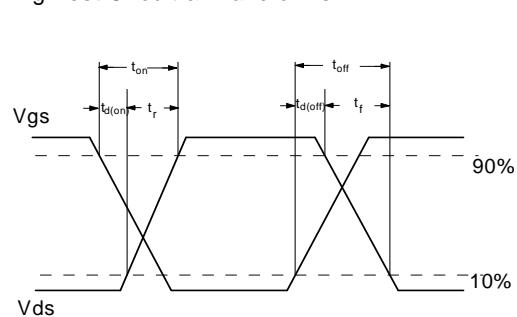
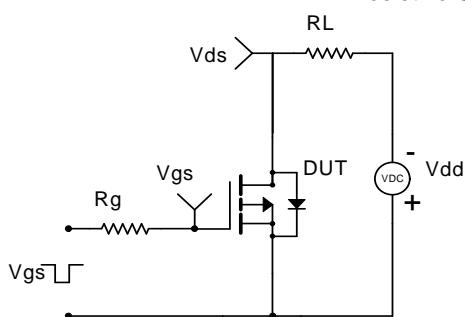
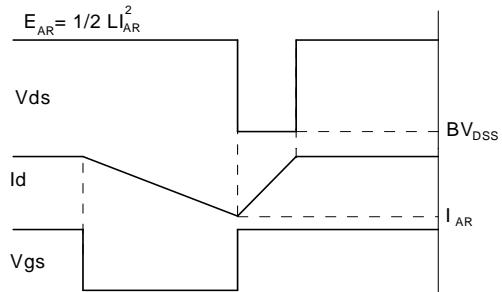
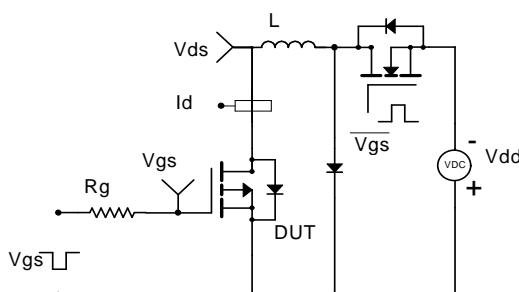
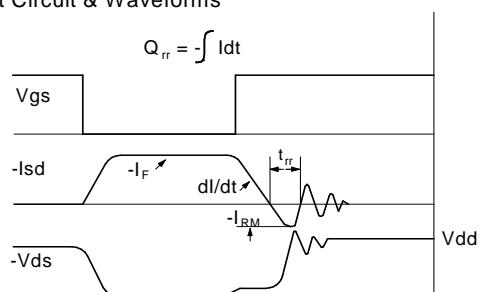
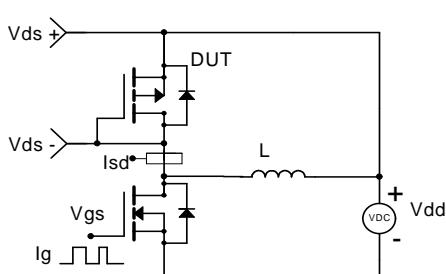
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P-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms


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